

DOCKET: CU-2417

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Takahiro IJIMA et al.

Serial No.: 09/736,864

Filed: December 14, 2000

For: INTERCONNECTION SUBSTRATE
HAVING METAL COLUMNS COVERED BY A
RESIN FILM AND MANUFACTURING
METHOD THEREOF

GRP ART UNIT : 2815

Ex.: CHU, C.

Certification under 37 C.F.R. §1.8(a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Commissioner for Patents, Washington, D.C. 20231 on January 30, 2003.

Vangelis Economou
Vangelis Economou

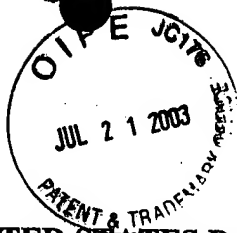
Commissioner for Patents
Washington, D.C. 20231

**RETRANSMITTAL OF CORRECTED DRAWINGS
FOR EXAMINER'S APPROVAL**

Sir:

Attached please find copies of drawing Fig. 2A (1 sheet), indicating by red ink the drawing correction for which the approval of the Examiner is respectfully requested. The drawing corrections have been requested by the Examiner in the Official Action dated June 25, 2002, and were disapproved when earlier submitted.

The identical changes have been made in respect of drawing Fig. 2A, that is, the lead line for the electrode 107 has been extended to indicate the correct element.



#15
Ltr to
Draft B
Jimmie Miller
8/11/03
approved
C.C.
10/10/03
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JUL 29 2003
TECHNOLOGY CENTER 2800

No new matter has been added to the drawings. The drawing figures are substantively identical to the drawings filed with the original application documents.

January 30, 2003

Respectfully submitted,



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